



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-09-23
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Emilio Castelli	<b>Representative Title</b>	APG MD CHAMPION
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L4995JTR	A6WL*UH45BA6	B	BO2A	2014-09-23
Amount	UoM	Unit type	ST ECOPACK Grade	
112.50	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	4.9x3.9x1.35	12	FLAT	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7A' exemption (other selected exemptions may apply)	true
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	A6WL*UH45BA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	3.894	mg	supplier	die	Silicon (Si)	7440-21-3		3.654	mg	938367	32480
Die or Dies (choose)				supplier	metallization	Aluminium (Al)	7429-90-5		0.027	mg	6934	240
Die or Dies (choose)				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	1027	36
Die or Dies (choose)				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.006	mg	1541	53
Die or Dies (choose)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.074	mg	19004	658
Die or Dies (choose)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	514	18
Die or Dies (choose)				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1541	53
Die or Dies (choose)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.019	mg	4879	169
Die or Dies (choose)				supplier	glass coating	Glass: Silicon Dioxide (SiO2)	7631-86-9		0.074	mg	19004	658
Die or Dies (choose)				supplier	polymer die coating	PIXI Gamma-butyrolactone	96-48-0		0.028	mg	7191	249
Leadframe	Copper & its alloys	31.543	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.168	mg	924706	259271
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.686	mg	21748	6098
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.041	mg	1300	364
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.036	mg	1141	320
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		1.612	mg	51105	14329
Die attach		3.305	mg	JIG - R	glue or tape (choose)	Lead (Pb)	7439-92-1	7a-Lead in high mel	3.156	mg	954917	28053
Die attach				supplier	glue or tape	Silver (Ag)	7440-22-4		0.083	mg	25113	738
Die attach				supplier	glue or tape	Tin (Sn)	7440-31-5		0.066	mg	19970	587
Bonding wire		0.195		supplier	wire	Gold (Au)	7440-57-5		0.195	mg	1000000	1733
encapsulation		72.160	mg	supplier	mold compound	Silica, vitreous	60676-86-0		57.728	mg	800000	513138
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		5.051	mg	69997	44898
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		2.886	mg	39994	25653
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		4.330	mg	60006	38489
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		0.866	mg	12001	7698
encapsulation				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		1.082	mg	14994	9618
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		0.217	mg	3007	1929
connections coating	Solder	1.403	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.403	mg	1000000	12471